

98426-YXX-XX-XXXLF

PLATING

- G : 0.76 GXT / 2μm MIN TIN ON TAIL
- S : 0.38 GXT / 2μm MIN TIN ON TAIL
- F : GOLD FLASH / 2μm MIN TIN ON TAIL
- T : 2μm MIN FULL TIN

UNDERPLATING 1.27μm NICKEL MIN.

LEAD FREE AND RoHS
COMPATIBLE, NOTE 6

STACK HEIGHT : XXX

- MIN= 104 (10.4MM)
- MAX= 290 (29.0MM)

NO. OF POS PER ROW, 03 TO 25

PIN STYLE	OAL
01	12.8
02	13.5
03	14.1
04	15.6
05	16.3
06	17.1
07	18.3
08	19.1
09	20.3
10	21.1
11	22.3
12	23.3
13	26.0
14	28.0
15	30.0
16	32.0

NOTES:

- MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC UL 94V-0, COLOR CREAM (SHROUD) AND BLACK(UNSHROUDED)
- MATERIAL TERMINAL: COPPER ALLOY
- BLIBOX PACKAGING
- SHROUDED RETENTION FORCE 3N MIN PER POSITION
- 0.3 MAX PROTRUSION FOR -03 TO 11
- RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2μm MINIMUM MATTE TIN OVER 1.27μm MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

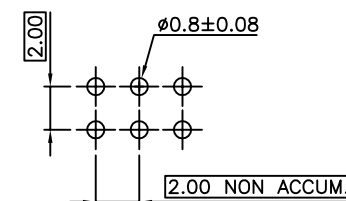
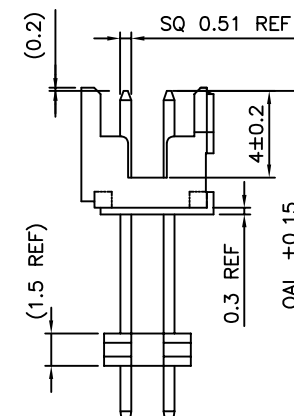
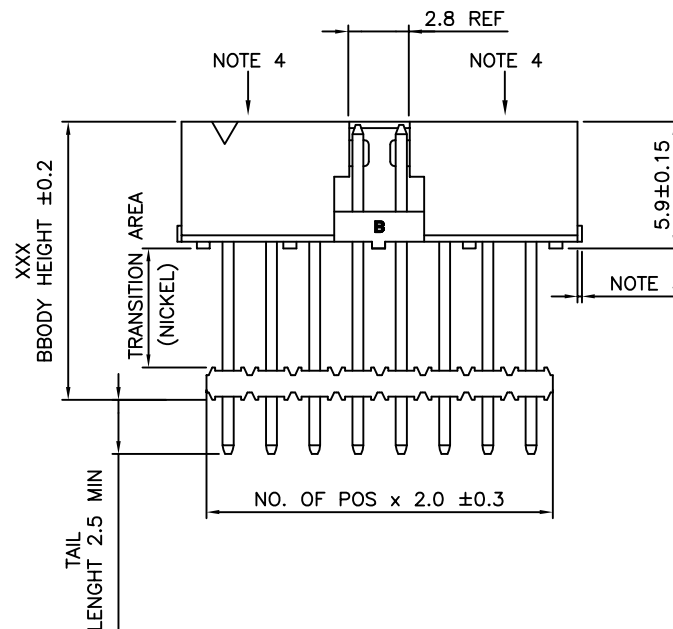
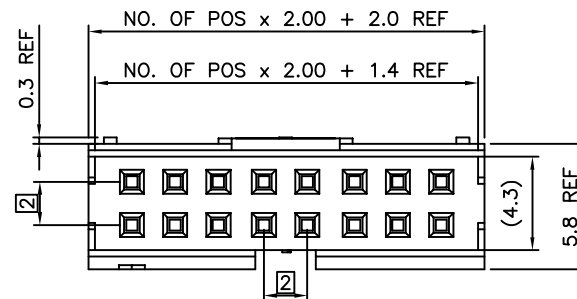
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920

d - LEGAL STATEMENT: SEE GS-22-008

- THIS PRODUCT IS NOT INTENDED TO BE USED THROUGH REFLOW PROCESS



RECOMMENDED HOLE PATTERN

mat'l. code				surface	tolerance	projection	product family	
				ISO 1302	ISO 406	ISO 101	MINITEK	
lfr	ecr no	dr	date	tolerances unless otherwise specified			title	
A	F09-0227	JCO	09.12.07	angles	X.X	±0.3	SHR STACKING	
B	F10-0067	JCO	10.06.29	linear	X.XX	±0.13	HEADER MINITEK	
					X.XXX	±0.05	scale 1:1	
				dr	L.MULIN	09.04.02	dwg no	
				engr	J.COMPAGNON	09.04.02	sheet 1 of 1	
				chr	JCO	09.12.07	size	
				appd	J.CO	09.12.07	98426	
sheet	revision						type	
index	sheet						CUSTOMER Drawing	

PDM: Rev:B

STATUS: Released

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